

## **APPARATUS AND METHOD OF PEELING A MULTI-LAYER SUBSTRATE**

### **ABSTRACT**

Methods are provided for processing a first substrate with a first major surface of the first substrate removably bonded to a first major surface of a carrier substrate. Example methods include the step of controlling a bend radius of the carrier substrate while peeling the carrier substrate from the first substrate. In further examples, methods include the step of peeling a leading peripheral edge of the carrier substrate from the first substrate with an attachment member while the attachment member pivots relative to an arm. Example peeling apparatus are also provided with an arm supporting a vacuum attachment member, wherein the arm is pivotally attached to a vacuum plate.

Fig. 1